BEST AVAILABLE COPY

	Query	Database	Date/Time
1	tile with array with MEM	USPAT; US-PGPUB; IBM_TDB	4/14/03 12:46
	("5371654" | "5432681" | "5510655" | "5544017" | "5574561" |		
6	"6052287").PN.	USPAT	4/14/03 12:44
2	6185107.URPN.	USPAT	4/14/03 12:45
1	tile with sub-array with MEM	USPAT; US-PGPUB; IBM_TDB	4/14/03 12:46
9	tile$3 with (array sub-array sub$2array or (sub adj array)) with MEM	USPAT; US-PGPUB; IBM_TDB	4/14/03 12:50
3	("5761350" | "6014240" | "6097857").PN.	USPAT	4/14/03 12:49
21	tile$3 with MEM	USPAT; US-PGPUB; IBM_TDB	4/14/03 12:50
218	(silicon with insulat$4) same MEM same substrate	USPAT; US-PGPUB; IBM_TDB	4/14/03 14:47
240	((silicon with insulat$4) or SOI) same MEM same substrate	USPAT; US-PGPUB; IBM_TDB	4/14/03 14:48
91	SOI same MEM same substrate	USPAT; US-PGPUB; IBM_TDB	4/14/03 14:49
	(((silicon with insulat$4) or SOI) same MEM same substrate) and		
85	mirror	USPAT; US-PGPUB; IBM_TDB	4/14/03 14:50
48	(SOI same MEM same substrate) and mirror	USPAT; US-PGPUB; IBM_TDB	4/14/03 15:52
2	("5629790" | "5742419").PN.	USPAT	4/14/03 14:51
2	(("5629790") or ("6445841")).PN.	USPAT; US-PGPUB; IBM_TDB	4/14/03 15:52
29	underbump with metallurgy	USPAT; US-PGPUB; IBM_TDB	4/15/03 18:51
1	(underbump with metallurgy) same MEM	USPAT; US-PGPUB; IBM_TDB	4/15/03 13:36
	("0557132" | "3244947" | "3259814" | "3274458" | "3316465" |		
	"3489965" | "3916080" | "3959577" | "3993123" | "4168480" | "4257905"		
	| "4449580" | "4511873" | "4563697" | "4565901" | "4897508" |		
20	"5046161" | "5325265" | "5475280" | "5627396").PN.	USPAT	4/15/03 11:46
	(etch$3 with insulat$5) same MEM same (SOI or (silicon near2		
35	insulator))	USPAT; US-PGPUB; IBM_TDB	4/15/03 13:41
	((etch$3 adj stop) with insulat$5) same MEM same (SOI or (silicon		
5	near2 insulator))	USPAT; US-PGPUB; IBM_TDB	4/15/03 13:49
3	(("6455841") or ("6025767") or ("5629790")).PN.	USPAT; US-PGPUB; IBM_TDB	4/15/03 13:50
29	underbump with metallurgy	USPAT; US-PGPUB; IBM_TDB	4/15/03 18:51
3	(underbump with metallurgy) and MEM	USPAT; US-PGPUB; IBM_TDB	4/15/03 18:53
214	(solder with bump) and MEM	USPAT; US-PGPUB; IBM_TDB	4/15/03 18:53
16	(solder with bump) and MEM and metallurgy	USPAT; US-PGPUB; IBM_TDB	4/15/03 20:48
2	(("6445841") or ("5629790")).PN.	USPAT; US-PGPUB; IBM_TDB	4/15/03 19:24
2521	etch$4 with thermal$4 with oxidat$4	USPAT; US-PGPUB; IBM_TDB	4/15/03 20:49
75	(etch$4 with thermal$4 with oxidat$4) and MEM	USPAT; US-PGPUB; IBM_TDB	4/15/03 20:49
2	(("6400550") or ("6367252")).PN.	USPAT; US-PGPUB; IBM_TDB	4/15/03 19:24